837LFWS



Lead-Free Water Soluble Flux

837LFWS is a neutral pH at room temperature that becomes highly activated at soldering temperatures. Post-soldering flux residues must be cleaned, but are easily removed with water.

This water soluble liquid flux is designed for wave soldering, surface mount assembly, and through-hole applications. It may be applied by spray, foam, or wave fluxing.

In liquid format, we also offer rosin-based flux, no-clean, halogen-free flux, and lead-free no-clean flux.

For paste flux, visit MG Chemicals' 8341 and 8342.

Features & Benefits

- · Water soluble flux for soldering
- Meets IPC J-STD-004B
- · For both leaded and lead-free solders
- · Excellent wetting and through-hole fill
- · Residues are easily removed with water
- RoHS-compliant and VOC-free

Available Packaging

Cat. No.PackagingNet Vol.Net Wt.837LFWS-1LBottle1 L846 g

Contact Information

MG Chemicals, 1210 Corporate Drive Burlington, Ontario, Canada L7L 5R6

Email: support@mgchemicals.com

Phone: North America: +(1)800-340-0772

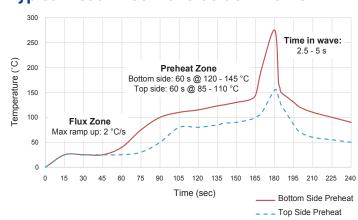
International: +(1) 905-331-1396 Europe: +(44)1663 362888



Properties

Flux Classification ORH1 Flux Type Organic Flux Activity High Complete Copper Mirror removal Corrosion Pass Cleaning Requirements Required Halides (by weight) 2.2 % $1.8 \times 10^{10} \Omega$ Suface Insulation Resistance (SIR)

Typical Lead-Free Wave Solder Profile



837LFWS



Application Instructions

Read the product SDS before using this product (downloadable at www.mgchemicals.com).

- **1.** Apply flux on the surface by dip, spray, foam, or brush application.
- **2.** Clean residue with MG 413B, 413C, 4140, 4050A, or 4140A flux removers.

Wave Solder Operating Parameters

Amount of Flux:

Foam 1000–2000 μ g/in² solids Spray 750–1500 μ g/in² solids

Foam Fluxing Parameters:

Foam Stone Pore Size $20-50~\mu m$ Flux Level Above Stone 25-40~mm Chimney Opening 10-13~mm Air Pressure $1-2~lb/in^2$

Top Side Preheat Temp. 85–110 °C

Bottom Side Preheat Temp. 35 °C

Conveyor-speed 1.2– 2.8 m/min

Contact Time in Solder 2.5–4.5 s

Solder Pot Temp.

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Sn96.5/Ag3.5	260-276 °C
Sn95/Ag5	280-296 °C
Sn99.3/Cu0.7	265-276 °C
SnAgCu	271–276 °C
Sn95/Sb5	280-296 °C

Foam Flux

- The foam fluxer should be provided with the compressed air
- · Flux tank must be always full
- Surface of the flux should be 0.5–1" above the top of the flux aerator or flux stone
- Adjust pressure to optimize foam height with a fine uniform foam head
- After fluxing, use an air knife to remove excess flux from the machine

To check for uniformity of spray flux coating, run a tempered glass plate provided by the machine manufactuer through the flux and preheat zones. Ensure to inspect the glass before the wave zone.

Storage and Handling

Store between 18 and 27 °C in a dry area, away from sunlight (see SDS).

Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.